Microwave Pulse Power Transistor 30 Watts Peak NPN 960–1215 MHz

Designed for 960-1215 MHz pulse common base amplifiers.

- · Guaranteed Performance at 960 MHz, 36 Vdc
 - Output Power = 30 Watts Peak
 - Gain = 9.0 dB Minimum
- 100% Tested for Load Mismatch at All Phase Angles with 10:1 VSWR
- · Silicon Nitride Passivated
- · Gold Metallized, Emitter Ballasted for Long Life
- Internal Input Matching for Broadband Operation
- · Hermetically Sealed Package

MRF10031H*



AVAILABLE AS

1) JANTX: MRF10031HX 2) JANTXV: MRF10031HXV 3) JANS: MRF10031HS 4) COML+: MRF10031HC

PACKAGE: Case 376B-02

MAXIMUM RATINGS

Rating	Symbol	Value	Unit
Collector-Emitter Voltage	V _{CES}	55	Vdc
Collector-Base Voltage	V _{CBO}	55	Vdc
Emitter-Base Voltage	V _{EBO}	3.5	Vdc
Collector Current - Peak (1)	Ic	3.0	Adc
Device Dissipation at T _C = 25 °C (1 & 2) Derate above 25 °C	PD	110 0.625	W mW/ °C
Operating Junction and Storage Temperature Range	T _J , T _{stg}	- 55 to + 200	°C

THERMAL CHARACTERISTICS

Characteristic	Symbol	Max	Unit
Thermal Resistance, Junction to Case (3)	R ₀ JC	1.6	°C/W

NOTES:

- 1. Under pulse RF operating conditions.
- 2. These devices are designed for RF operation. The total device dissipation rating applies only when the devices are operated as RF amplifiers
- 3. Thermal Resistance is determined under specified RF operating conditions by infrared measurement techniques.

^{*} Motorola Preferred Device. **Preferred** devices are Motorola recommended choices for future use and best overall value. Teflon is a registered trademark of du Pont de Nemours & Co., Inc.



(continued)

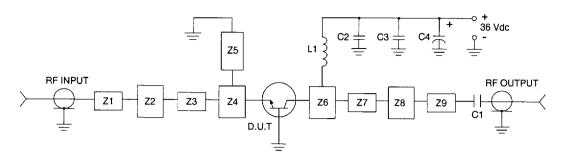
ELECTRICAL CHARACTERISTICS (T_A = 25 °C unless otherwise noted)

Characteristic	Symbol	Min	Max	Unit
OFF CHARACTERISTICS				
Collector-Emitter Breakdown Voltage (I _C = 25 mAdc, V _{BE} = 0)	V _(BR) CES	55	-	Vdc
Collector-Base Breakdown Voltage (I _C = 25 mAdc, I _E = 0)	V _(BR) CBO	55	_	Vdc
Emitter-Base Breakdown Voltage (I _E = 5.0 mAdc, I _C = 0)	V _{(BR)EBO}	3.5	-	Vdc
Collector Cutoff Current (V _{CB} = 36 Vdc, I _E = 0)	СВО	-	2.0	mAdc
ON CHARACTERISTICS				
DC Current Gain (I _C = 500 mAdc, V _{CE} = 5.0 Vdc)	h _{FE}	20	_	-
FUNCTIONAL TESTS (10 μs Pulses at 50% duty cycle for 3.5 ms, overall of	duty cycle = 25%)			
Common-Base Amplifier Power Gain (V _{CC} = 36 Vdc, P _{OUT} = 30 W Peak, f = 960 MHz)	G _{PB}	9.0	_	dB
Collector Efficiency (V _{CC} = 36 Vdc, P _{OUT} = 30 W Peak, f = 960 MHz)	η	40	_	%
Load Mismatch (V _{CC} = 36 Vdc, P _{OUT} = 30 W, f = 960 MHZ VSWR = 10:1 All Phase Angles)	ψ No Degradation in		adation in Out	put Power

ASSURANCE TESTING (Pre/Post Burn-In) Burn-In Test Conditions: $V_{CB} \ge 10$ Vdc, $T_J = 162.5$ °C + 12.5 °C

Characteristic	Symbol	Min	Max	Unit
Collector Cutoff Current (V _{CB} = 36 Vdc, I _E = 0)	СВО	-	2.0	mAdc
DC Current Gain (I _C = 500 mAdc, V _{CE} = 5.0 Vdc)	hFE	20	-	-

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C1 - 75 pF 100 mil Chip Capacitor

C2 - 39 pF 100 mil Chip Capacitor

 $C3 - 0.1 \mu F$

 $C4 - 1000 \mu F$, 50 Vdc, Electrolytic

L1 – 3 turns #18 AWG, 1/8" ID, 0.18" Long Z1- Z9 – Microstrip, see details below Board Material – 0.030" GlassTeflon $^{\circledR}$ 2 Oz. Copper, \in_{Γ} = 2.55

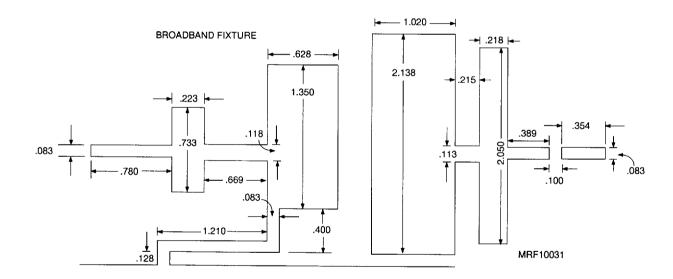


Figure 1. Test Circuit

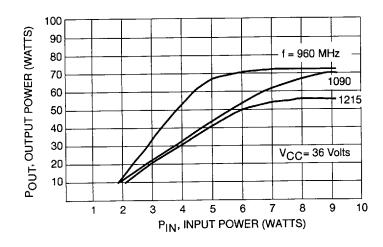
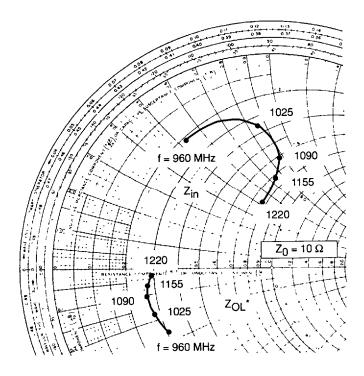


Figure 2. Output Power versus Input Power



 P_{OUT} = 30 W Pk, V_{CC} = 36 V

f MHz	Z _{IN} OHMS	Z _{OL} * OHMS
960	2.05 + j5.2	2.9 - j2.35
1025	2.67 + j6.34	2.55 - j1.3
1090	4.0 + j7.1	2.52 - j0.9
1155	5.5 + j6.2	2.6 - j0.6
1220	5.7 + j4.3	2.8 - j0.3

Z_{OL}* is the conjugate of the optimum load impedance into which the device operates at a given output power, voltage and frequency.

Figure 3. Series Equivalent Input/Output Impedances

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TABLE 1. SCREENING REQUIREMENTS

SCREEN	METHOD	нх	HXV
Internal visual inspection (precap)	2072	N/A	100%
2. High temperature non-operating life	1032	100%	100%
3. Temperature cycling	1051	100%	100%
4. Constant Acceleration (Gold wires only)	2006	100%	100%
5. Hermetic seal (Fine and Gross)	1071	100%	100%
6. Establish Unit Identity	none	100%	100%
7. Interim electrical parameters	as specified	100%	100%
8. High temperature reverse bias (HTRB)	1039	100%	100%
9. Interim electrical parameters	as specified	100%	100%
10. Power burn-in	1039	100%	100%
11. Final electrical parameters	as specified	100%	100%
12. Hermetic seal (Fine and Gross)	1071	optional	optional

GROUP A TEST SEQUENCE

		Subgroups				
A1	A2	A3	A4			
	Type of Test					
Visual/Mechanical Package: Dimensions, Marking	DC Tests V(BR)CBO V(BR)CES V(BR)EBO ICBO hFE	Hi/Lo Temp Not Applicable	AC Tests G _{PB} η			

GROUP B TEST SEQUENCE

		S	ubgroups		
B1**	B2*	B3*	B4	B5	B6*
		Ту	pe of Test		
Solderability (1)	Temp. Cycling	Steady State Operating Life	Decap Visual	Not Required	High Temp. Life (Non-Operating)
Resistance to	Hermetic Seal	, ,			(Non operating)
Solvents	Fine				İ
	Gross	Bond Strength			

 $^{^{\}star}$ The tests in this subgroup are preceded and followed by $I_{\mbox{\footnotesize{CBO}}}$ and $h_{\mbox{\footnotesize{FE}}}$ electrical tests.

GROUP C TEST SEQUENCE*

		S	Subgroups		
C1	C2**	C3**	C4	C5	C6**
		Т	ype of Test		
Physical Dimensions	Thermal Shock (Glass Strain) Terminal Strength Hermetic Seal Moist. Resistance	Mech. Shock Vibration (Var. Freq.) Const. Accel.	Salt Atmosphere	Not Applicable	Steady State Op Life

 $^{^{\}star}$ Group C is performed on the initial lot and requalification only.

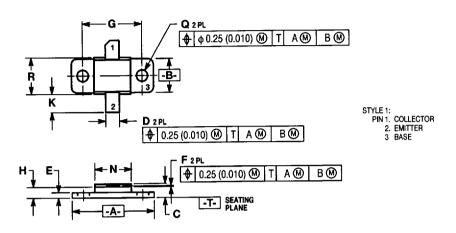
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^{**} Separate samples may be used for each test.

⁽¹⁾ Omit Steam Aging requirements.

^{**} The tests in this subgroup are preceded and followed by $I_{\mbox{\footnotesize{CBO}}}$ and $h_{\mbox{\footnotesize{FE}}}$ electrical tests.

OUTLINE DIMENSIONS



- 1. DIMENSIONING AND TOLERANCING PER ANSI
- Y14.5M, 1982. 2. CONTROLLING DIMENSION: INCH.
- 3. 376B-01 OBSOLETE, NEW STANDARD 376B-02.

	MILLIM	ETERS	INC	HES	
DIM	MIN	MAX	MIN	MAX	
Α	22.61	23.11	0.890	0.910	
В	9.40	10.16	0.370	0.400	
Ç	3.69	4.06	0.145	0.160	
۵	3.56	4.06	0.140	0.160	
E	1.40	1.65	0.055	0.065	
F	0.08	0.15	0.003	0.006	
G	16.51 BSC 0.650 BS		BSC		
н	2.80	3.30	0.110	0.130	
K	4.57	5.59.	0.180	0.220	
N	9.91	10.41	0.390	0.410	
a	2.93	3.42	0.115	0.135	
R	9.91	10.41	0.390	0.410	

CASE 376B-02

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